placing a substrate in a sputter

simultaneously sputtering first and second metal targets to form an anti-microbial film on the substrate

FIG. 1

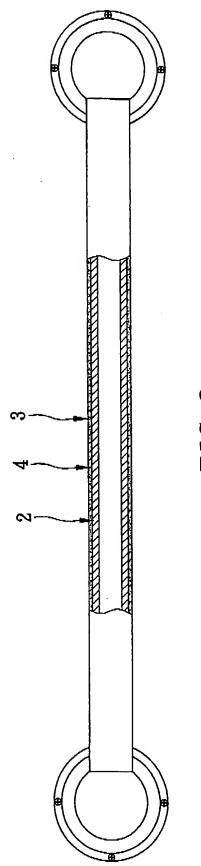


FIG. 2